

IN THE CLAIMS

Please amend the claims as follows:

Claim 1 (Currently Amended): A method ~~Method~~ for molecular adhesion of a second electronic compound on a first electronic compound, comprising:

coating the a contact surface of the first electronic compound containing a polymer,
~~comprising the coating,~~ with a bonding layer[[,]] ; and

~~of at least some of the surface of the polymer contained at the surface of the first electronic compound, with the molecular adhesion taking place between said bonding layer~~
and molecularly adhering the second electronic compound to the bonding layer of the contact surface of the first electronic compound, wherein

the contact surface of the first electronic compound comprises a hydrocarbon polymer, and

at least some of the hydrocarbon polymer is coated with the bonding layer.

Claim 2 (Currently Amended): The method ~~Method~~ according to claim 1, further comprising:

~~the cleaning of the a contact surface of the second electronic compound;~~ and/or

[[its]] coating the contact surface of the second electronic compound with a layer similar to the bonding layer, wherein the bonding layer coating the contact surface of the second electronic compound is similar to the bonding layer coating the first electronic compound.

Claim 3 (Currently Amended): The method ~~Method~~ according to claim 1, further comprising the thinning of the second electronic compound after adhesion thereof to the bonding layer.

Claim 4 (Currently Amended): The method ~~Method~~ according to claim 1, further comprising ~~the heat treatment of~~ heat treating the ~~an~~ assembly of the two compounds after adhesion.

Claim 5 (Currently Amended): The method ~~Method~~ according to claim 1, wherein a thickness of the coating ~~[[is]]~~ produced by deposition of ~~[[a]]~~ the bonding layer ~~having a~~ thickness is between 50 and 300 nm.

Claim 6 (Currently Amended): The method ~~Method~~ according to claim 1 further comprising:

~~[[the]]~~ polishing of the bonding layer; and/or

~~its activation~~ activating the bonding layer, prior to the molecular adhesion.

Claim 7 (Canceled).

Claim 8 (Currently Amended): The method ~~Method~~ according to claim 1, further comprising ~~[[the]]~~ cross-linking of the polymer prior to the coating thereof.

Claim 9 (Currently Amended): The method ~~Method~~ according to claim 1, wherein the bonding layer consists of silicon oxide.

Claim 10 (Currently Amended): A method ~~Method~~ for producing an array of stacked electronic compounds comprising:

applying the method of claim 1 to adhere the development of at least one first electronic compound ~~so that the surface of the first electronic compound at least partially consists of a polymer, and the adhesion on this surface of to [[a]] at least one second electronic compound according to the method defined in claim 1.~~

Claim 11 (Currently Amended): A three-dimensional ~~Three-dimensional~~ array of electronic compounds comprising a plurality of interface layers, wherein each of the interface layers is at least equal to ~~[[the]]~~ a surface of the array at the level of said interface layer, ~~so that~~ wherein at least some of the interface layers directly separate a hydrocarbon polymer from at least one electronic component.

Claim 12 (Currently Amended): The three-dimensional array ~~Array~~ according to claim 11, consisting of a stack of electronic compounds, wherein each compound has ~~[[the]]~~ a same shape and/or size as ~~[[the]]~~ an adjacent compound ~~from which it~~ and each compound and adjacent compound ~~[[is]]~~ are separated by an interface layer.

Claim 13 (Currently Amended): The three-dimensional array ~~Array~~ according to claim 11, wherein the interface layers consist of at least one material selected from the group consisting of silicon oxide, silicon nitride ~~and/or~~ and silicon oxynitride.

Claim 14 (Currently amended): The method ~~Method~~ according to claim 1, wherein the coating is produced by deposition of a bonding layer made of silicon oxide having a thickness between 50 and 300 nm.

Claim 15 (Currently amended): The method ~~Method~~ according to claim 14, further comprising:

[[the]] polishing and/or

~~the activation of~~ activating the silicon oxide layer.

Claim 16 (Currently amended): The method ~~Method~~ according to claim 15, further comprising [[the]] cross-linking of the polymer prior to the coating thereof.

Claim 17 (Currently amended): A method ~~Method~~ for producing an array of stacked electronic compounds, comprising:

applying the method of claim 14 to adhere ~~the development of~~ at least one first electronic compound ~~so that the surface of the first electronic compound at least partially consists of a polymer, and the adhesion on this surface of a~~ to at least one second electronic compound ~~according to the method defined in claim 16.~~

Claim 18 (Currently amended): A method ~~Method~~ for molecular adhesion of a second electronic compound on a first electronic compound, comprising:

crosslinking a hydrocarbon polymer on a contact surface of the first electronic compound;

[[the]] coating at least some of the contact surface of the first electronic compound ~~containing a polymer, comprising the cross-linking of the polymer, the coating with~~ at least one material selected from the group consisting of silicon oxide, silicon nitride ~~and/or~~ and silicon oxinitride, ~~of at least some of the surface of the polymer contained at the surface of the first electronic compound,~~

[[the]] polishing and/or ~~activation of said~~ activating the silicon layer[[,]]; and
molecularly adhering ~~with the molecular adhesion taking place between said silicon~~
~~layer and the second electronic compound~~ to the contact surface of the first electronic
compound.

Claim 19 (Currently amended): The method ~~Method~~ according to claim 18, further
comprising ~~the heat treatment of~~ heat treating [[the]] an assembly of the two electronic
compounds after adhesion.

Claim 20 (Currently amended): The method ~~Method~~ according to claim 19, further
comprising [[the]] thinning of the second electronic compound after adhesion thereof to the
first electronic compound.